

## Quality and Reliability - Frequently Asked Questions

### What is the ESD rating of the PCI products and what methods were followed?

- Human Body Model (HBM): 2000 volts. The method used was JESD22-A114-B.
- Charge Device Model (CDM): 500 volts. The method used was JESD22-C101C.

### Is the device package moisture sensitive?

- Yes.

### What is the moisture sensitivity level (1-6) of the products?

- NET2000 series family: MSL3 (except: 2252/ 2890: MSL2; 2270/ 2272/2280 TQFP packages and 2272 BGA Package: MSL4)
- PCI6000 series family: MSL3
- PCI9000 series family: MSL3 (except: PCI9050-1F: MSL4 and PCI9030 BGA package: MSL2)
- PEX8000 series family: MSL3
- PEX8600 series family (PBGA package: 8604/ 8606/ 8608/ 8609 /8614/ 8615/8618 /8619): MSL3
- PEX8600 series family (FCBGA package: 8612 8616 8624 8632 8647 8648): MSL4
- PLX Storage and Connectivity products (formerly Oxford Semiconductor) part numbers with the prefix OX, FW, TD: MSL3

### What is the safe exposure time after opening the moisture bag?

- 1 year for Level 2 moisture sensitivity.
- 168 hours for Level 3 moisture sensitivity.
- 72 hours for Level 4 moisture sensitivity.

### Does the part have to be baked prior to use?

- No. If the part was baked, vacuum sealed and floor time did not exceed specified exposure time.

### Does the tray meet the JEDEC standard and is it bakeable?

- Yes. The tray meets the JEDEC requirements and is bakeable up to a maximum of 125°C.

### How is the thermal resistance calculated?

- It can be calculated from the ambient temperature  $T_a$ , the thermal resistance ( $\Theta_{tj-a}$ ) of the package, and the power consumption PD.
- The chip temperature ( $T_j$ ) =  $T_a + (PD \times \Theta_{tj-a})$  (°C) where
  - $T_j$  = chip junction temperature
  - $T_a$  = ambient temperature
  - PD = power consumption
  - $\Theta_{tj-a}$  = thermal resistance

### Are all the parts qualified and are data available?

- All parts have been qualified. Either specific data or "generic" data is available upon request.

### How is the device qualified?

- The product is submitted through various electrical and environmental tests as described in the applicable JEDEC specifications and/or MIL-STD-883.

### Is generic or product-specific data available?

- Yes. Both types of data are available depending on the product.

**How may I obtain generic or product-specific data?**

- The data is either available at [www.plxtech.com](http://www.plxtech.com) or may be requested of your local PLX Sales Representative or by sending an email to [QASurvey@plxtech.com](mailto:QASurvey@plxtech.com). The data is considered proprietary and has limited distribution for customers who have received approval from the PLX Sales Department.

**What is the FIT rate for PLX devices?**

- Please refer to the Qualification report or request this information via [QASurvey@plxtech.com](mailto:QASurvey@plxtech.com).

**How often are products qualified and are there on-going product monitors?**

- Once the product is qualified there are subsequent monitors on a periodic basis. This monitor will usually have a subset of tests derived from the new product introduction qualification testing. Should at least any of these changes occur, a re-qualification is required:

1. New product release
2. Major process change
3. Relocation of wafer fabrication or assembly plant
4. New equipment
5. Change in wafer size
6. New process

**What is the Flammability rating of the devices?**

- For QFP & BGA packages, the rating is UL94 V-O.

**Are PLX parts Industrial temperature qualified?**

- In general, Yes. Industrial temperature for PLX products are -40°C to +85°C (Ta)

**How are QFP leads inspected?**

- The leads are inspected using either by an optical or laser based lead scanner. The lead scanner inspects the leads for pitch, skew, bent leads, co-planarity and missing leads. Inspection parameters are taken directly from the product data book.

**What does the part number coding mean?**

field-1	field-2	field-3	field-4	field-5	field-6	field-7
XXX	XXXX	XX	XX	X	X	X or XX

1. Device Class (e.g., **PEX**8548-AA25BI G)
2. Part Number (e.g., PEX**8548**-AA25BI G)
3. Device Revision (e.g., PEX8548-**AA**25BI G)
4. Maximum Operating Frequency (in MHz) (e.g., PEX8548-AA**25**BI G)
5. Packaging Technology (B=BGA, P=PQFP) (e.g., PEX8548-AA25**B**I G)
6. Operational Temperature Range (I=industrial, C=commercial) (e.g., PEX8548-AA25BI**I** G)
7. RoHS status: Lead (no suffix)/ Lead-free (suffix LF or F) or Green (suffix G) (e.g., PEX8548-AA25BI **G**: Green part)

**What does the marking mean?**

- |        |                          |
|--------|--------------------------|
| Line 1 | PLX Logo                 |
| Line 2 | PLX Part Number          |
| Line 3 | Date Codes, ESD Triangle |
| Line 4 | Lot#, Country of Origin  |